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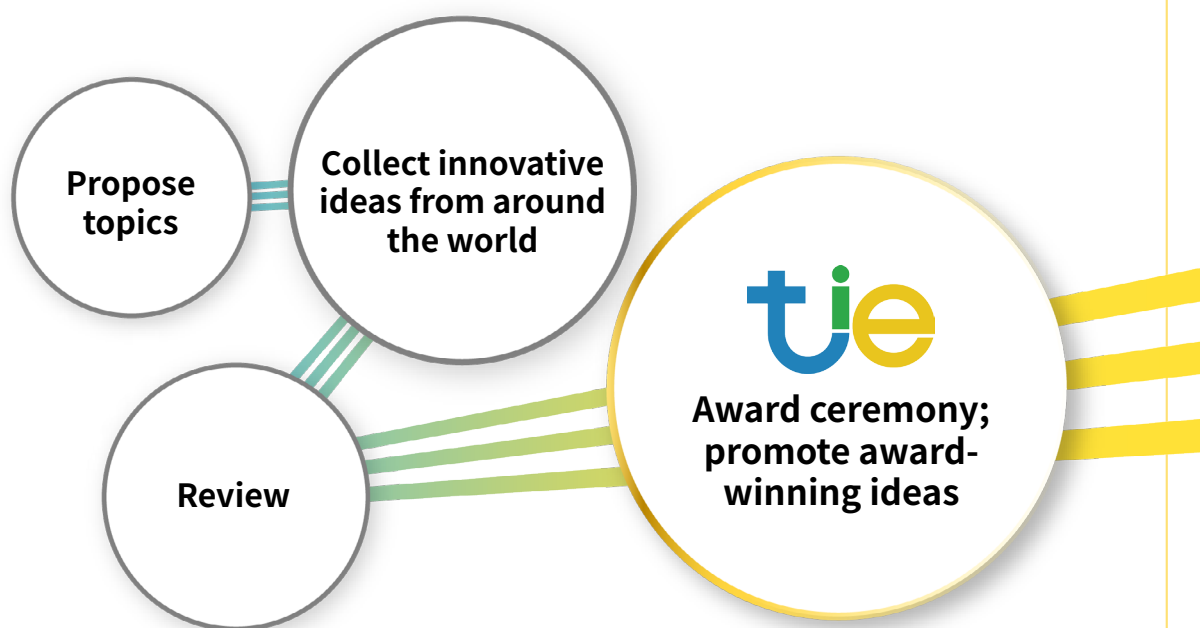
Taiwan Innotech Expo
Tech Innovation Excellence Award

GLOBAL TECH AND INDUSTRY TIE WITH TAIWAN

What is TIE Award

The Tech Innovation Excellence Award (“TIE Award”) is a contest organized by Taiwanese government, including the Ministry of Science and Technology (MOST) and the Ministry of Economic Affairs. Underneath the “Taiwan Innotech Expo” , TIE Award offers a stage to celebrate cutting-edge technologies. We would like to invite startups, research institutions and legal person to gather in Taiwan, showing their innovations and grabbing the chance to work with Taiwanese tech giants.

Taiwan has a world-class industry clusters which is very useful for startups overseas if they need support for their new ideas or new business models, so TIE Award will build up a bridge for global startups and Taiwanese high-tech companies, and let both sides can work together to create new businesses and benefit each other.



Organizer:



Co-organizer:



Taiwan Innotech Expo
台灣創新技術博覽會



NAR Labs National Applied Research Laboratories
Taiwan Semiconductor Research Institute



TechOrange 科技報橘

Categories

TIE Award is focused on **semiconductor technology** that fits within one of the designated 8 application categories as follows:

AI, AIoT	Sensors	Comms/Satellite	Efficient energy conservation
Smart manufacturing	Autonomous vehicles	New energy	Other

Competition Schedule (in Taiwan Standard Time) August-September

Before 8/7	Online registration	Applicants need to complete online registration and submit an application form, concept paper, and supplementary material
August 8-10	Eligibility review	The organizer conducts the eligibility review in accordance with the registration guidelines and confirms the competition topics
August 11-21	Initial review (concept paper)	The applicants' concept papers are reviewed, and a shortlist of contenders is determined
September 1-2	Secondary review (presentation)	A demo and Q&A are held either virtually or in person. The presenter must deliver the entirety of the presentation in English. In total, the presentation and Q&A will take 20 minutes (10 minutes of presentation and demo, 10 minutes of Q&A)
Mid-September	The result of TIE Award will be announced in mid-September	

October 13-15



1. The winner's solution will be presented at the Taiwan Innotech Expo (TIE) from October 13 to 15 2022.
2. The Pitch Day(only the winning teams participate) will be held in October 15, 2022.
3. The award ceremony is held during the exhibition period.

Entry Criteria

For purpose of TIE Award, “technology” is defined as hardware or software R&D outcomes. “Applicant” is defined as **startup, legal person, or academic/research institution.**

- Startups must have been legally registered no earlier than January 1, 2014.
- Startups, legal person or any other institution that are Chinese or registered in China or in the third-area who invested by China may not be accepted.
- Applicants must not receive over 30% funds from companies in the third-area in Article 3 of “Regulations Governing the Permission of Investment by Nationals in Mainland Area” . (Third-area company refers to Mainland Area individual, legal person, organization or any other institution in aggregate, who directly or indirectly holds more than 30% of the company's shares or contributes more than 30% of the total capital; or has control over the third-area company).

Applicants must own the intellectual property rights, or have received legal authorization to use the technology or solution.

Applicants must submit the application online (initial review) and give a presentation (secondary review).



Application information

www.futuretech.org.tw

Global tech and industry tie with Taiwan

Review Committee & Criteria

Members of the Review Committee are representatives from Taiwan's semiconductor industry, professionals in the field of international VC, and government experts. The award-winning team is selected after an initial and secondary review.

Review criteria

40%

Application innovation

1. Innovation when applied to an emerging field
2. Demonstrate groundbreaking performance in production, design, and new material application
3. Able to include diverse innovation and integrate interdisciplinary thinking

30%

Value creation

1. The potential to promote technological innovation and benefit society
2. Promote new industry chains or contributes to industry upgrading
3. Attract derivative investments or creates high economic value

30%

Local integration

1. How the solution can be applied to solve problems in the world but can ride on one of Taiwan's technology platforms or partner with a Taiwanese company
2. The potential to strengthen the competitiveness of industries in Taiwan or able to effectively resolve or mitigate challenges facing Taiwan's industries

Award Benefits

1. Million-dollar award

- 1st place: USD\$ 30,000
- 2nd place: USD\$ 20,000
- 3rd place: USD\$ 10,000
- 7 honorable mentions: USD\$ 7,000

2. Exposure

- TIE marketing resources, including physical and online exhibitions and promotional material
- Directly promote solutions to investors on Pitch Day
- International news coverage

3. Award ceremony and official pin

- TIE Awards trophy
- Winners can use the TIE Award pin, authorized by the organizers, for further promotion

4. Business opportunities

- The chance to work with Taiwan's top semiconductor companies
- Coworking space for further business promotion at Taiwan Tech Area (TTA)
- Shortlisted teams after the secondary review but do not win at finals are awarded a booth in the international section of Taiwan Innotech Expo, resources for coworking space in TTA, and access to matchmaking events

Obligations

1. The winning teams must exhibit in person at the TIE Award Area of Taiwan Innotech Expo and participate in Pitch Day events. Teams that fail to travel to Taiwan will forfeit all awards and prizes won.
2. The winning teams must pitch in matchmaking event that is to take place during the Taiwan Innotech Expo(the organizer will invite VC and domestic semiconductor R&D representatives to participate, which will promote technological collaborations and attract talent).
3. The winning teams must submit relevant materials in conjunction with the promotional events held by the TIE Award.